

### 870 MHz CATV 18 dB PUSH-PULL AMPLIFIER

#### DESCRIPTION

The MC-7831 is a GaAs Multi-chip Module designed for use in CATV applications up to 870 MHz. This unit has low distortion, low noise figure and return loss across the entire frequency band.

Reliability and performance uniformity are assured by our stringent quality and control procedures.

#### FEATURES

- Low distortion
- High linear gain  $G_L = 18.0 \text{ dB MIN. @ } f = 870 \text{ MHz}$
- Low return loss

#### ORDERING INFORMATION

Part Number	Order Number	Package	Supplying Form
MC-7831	MC-7831-AZ	7-pin special with heatsink (Pb-Free)	50 pcs MAX./Tray

**Remark** To order evaluation samples, contact your nearby sales office.

Part number for sample order: MC-7831

#### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = +25°C)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V <sub>DD</sub>	30	V
Input Voltage <sup>Note</sup>	V <sub>i</sub>	65.0	dBmV
Operating Case Temperature	T <sub>c</sub>	-30 to +100	°C
Storage Temperature	T <sub>stg</sub>	-40 to +100	°C

**Note** In case of single tone

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.  
Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

**RECOMMENDED OPERATING CONDITIONS ( $Z_s = Z_L = 75 \Omega$ )**

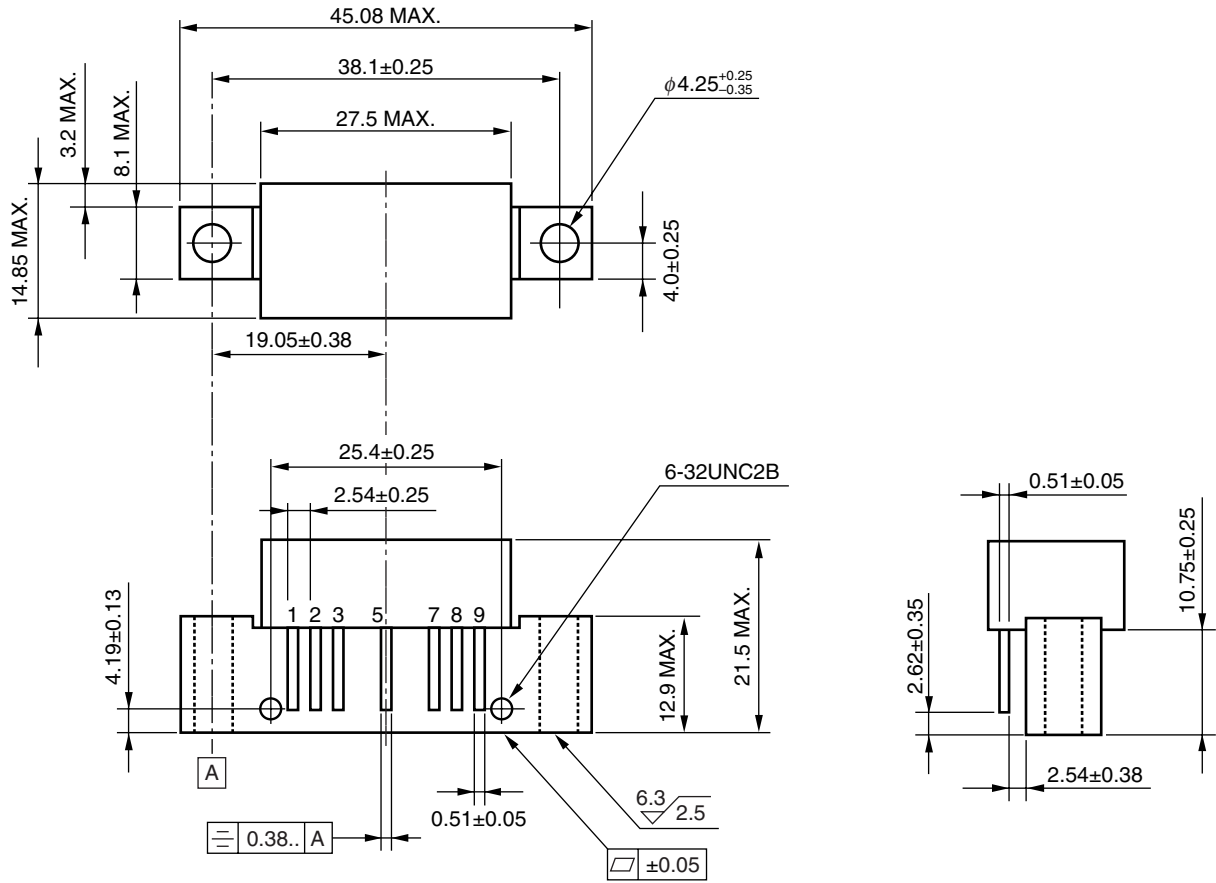
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Supply Voltage	$V_{DD}$		23.5	24.0	24.5	V
Input Voltage	$V_i$	110 channel, Flat	-	21.0	27.5	dBmV
Operating Case Temperature	$T_C$		-30	+25	+85	°C

**ELECTRICAL CHARACTERISTICS ( $T_C = 30 \pm 5^\circ\text{C}$ ,  $V_{DD} = 24 \text{ V}$ ,  $Z_s = Z_L = 75 \Omega$ )**

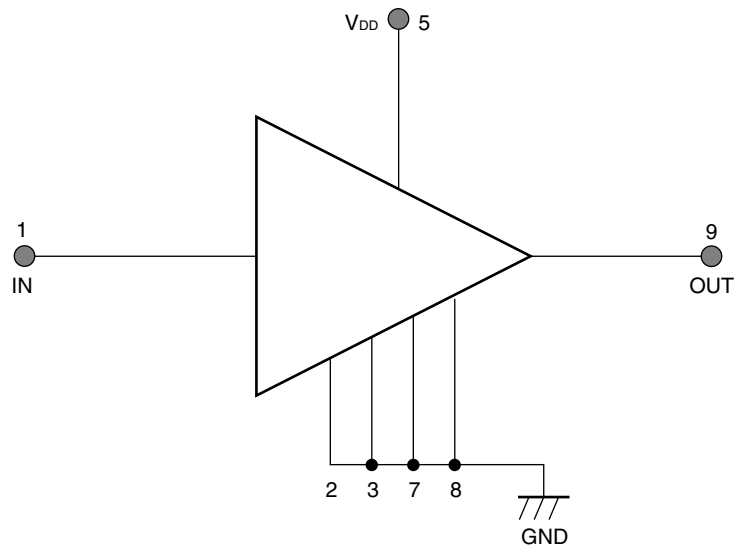
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Linear Gain	$G_L$	$f = 870 \text{ MHz}$	18.0	-	19.0	dB
Gain Slope	$G_{\text{slope}}$	$f = 40 \text{ to } 870 \text{ MHz}$	0.2	-	1.0	dB
Gain Flatness	$G_{\text{flatness}}$	$f = 40 \text{ to } 870 \text{ MHz}$ , Peak to valley	-	-	0.7	dB
Noise Figure 1	$NF_1$	$f = 50 \text{ MHz}$	-	-	6.5	dB
Noise Figure 2	$NF_2$	$f = 870 \text{ MHz}$	-	-	7.0	dB
Operating Current	$I_{DD}$	$P_{in} = \text{None}$	180	-	240	mA
★ Composite Triple Beat	CTB	110 channel, $V_o = 44 \text{ dBmV}$ , Flat	-	-	-57	dBc
★ Cross Modulation	XM		-	-	-50	dBc
★ Composite 2nd Order Beat	CSO		-	-	-57	dBc
Input / Output Return Loss 1	$RL_1$	$f = 40 \text{ to } 160 \text{ MHz}$	20	-	-	dB
Input / Output Return Loss 2	$RL_2$	$f = 160 \text{ to } 320 \text{ MHz}$	19	-	-	dB
Input / Output Return Loss 3	$RL_3$	$f = 320 \text{ to } 640 \text{ MHz}$	17.5	-	-	dB
Input / Output Return Loss 4	$RL_4$	$f = 640 \text{ to } 870 \text{ MHz}$	16	-	-	dB

PACKAGE DIMENSIONS

7-PIN SPECIAL WITH HEATSINK (UNIT: mm)



PIN CONNECTION



**NOTES ON CORRECT USE**

- (1) The space between PC board and root of the lead should be kept more than 1 mm to prevent undesired stress to the lead and also should be kept less than 4 mm to prevent undesired parasitic inductance.  
Recommended that space is 2.0 to 3.0 mm typical.
- (2) Recommended torque strength of the screw is 59 to 78 Ncm.
- (3) Form the ground pattern as wide as possible to minimize ground impedance.  
(to prevent undesired oscillation)  
All the ground pins must be connected together with wide ground pattern to decrease impedance difference.

**RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Partial Heating	Peak temperature (pin temperature) : 350°C or below <sup>Note</sup> Soldering time (per pin of device) : 3 seconds or less	—

**Note** The point of pin part heating must be kept more than 1.2 mm distance from the root of lead.

When the product(s) listed in this document is subject to any applicable import or export control laws and regulation of the authority having competent jurisdiction, such product(s) shall not be imported or exported without obtaining the import or export license.

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- M8E 00.4-0110

<p><b>Caution</b></p>	<p>GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> <li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.               <ol style="list-style-type: none"> <li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> <li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li> </ol> </li> <li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li> <li>• Do not lick the product or in any way allow it to enter the mouth.</li> </ul>
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► For further information, please contact

**NEC Compound Semiconductor Devices, Ltd.** <http://www.ncsd.necel.com/>

E-mail: [salesinfo@ml.ncsd.necel.com](mailto:salesinfo@ml.ncsd.necel.com) (sales and general)

[techinfo@ml.ncsd.necel.com](mailto:techinfo@ml.ncsd.necel.com) (technical)

Sales Division TEL: +81-44-435-1573 FAX: +81-44-435-1579

**NEC Compound Semiconductor Devices Hong Kong Limited**

E-mail: [ncsd-hk@elhk.nec.com.hk](mailto:ncsd-hk@elhk.nec.com.hk) (sales, technical and general)

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309

Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859

Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

**NEC Electronics (Europe) GmbH** <http://www.ee.nec.de/>

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

**California Eastern Laboratories, Inc.** <http://www.cel.com/>

TEL: +1-408-988-3500 FAX: +1-408-988-0279